July 13, 2017

Invensas' Dr. Paul Enquist Wins 3D InCites Lifetime Achievement Award

Additionally, Invensas Named "Fabless of the Year," and its DBI Technology Captures "Process of the Year" Award at Industry Awards Reception

SAN FRANCISCO--(BUSINESS WIRE)-- Xperi Corporation (Nasdaq:XPER), ("Xperi" or the "Company") is proud to announce its wholly owned subsidiary, Invensas, the world's leading provider of advanced semiconductor packaging and 3D interconnect technologies, captured three 3D InCites Awards honors, revealed at a reception last night. Dr. Paul Enquist, vice president of 3D R&D, received the prestigious Lifetime Achievement Award for his numerous innovations and contributions to the semiconductor industry, Invensas was honored as Fabless of the Year, and its Direct Bonding Interconnect (DBI®) technology won Process of the Year. The 3D InCites Awards were established in 2013 to acknowledge companies and individuals who were instrumental in the development and commercialization of semiconductor 3D integration technologies. The awards were determined by an online voting process amongst industry professionals.

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Dr. Paul Enquist, vice president of 3D R&D at Invensas, a subsidiary of Xperi Corp., captured the 2017 3D InCites Lifetime Achievement Award. (Photo: Business Wire)

2017 3D InCites Lifetime Achievement Award - Dr. Paul Enquist

For more than 30 years, Dr. Enquist has been a pioneer in developing cutting-edge semiconductor technologies. As a co-founder of Ziptronix, acquired by the Company in 2015, Dr. Enquist is the key inventor of ZiBond® and DBI low temperature bonding and 3D integration technologies, which were integrated with Invensas' portfolio of packaging and interconnect solutions. These technologies have been commercially adopted in more than one billion semiconductor devices across a wide range of mobile, consumer, industrial and automotive products.

"Dr. Enquist's 3D InCites Lifetime Achievement Award is extremely well deserved," said Craig Mitchell, president of Invensas. "His innovations have resulted in foundational 3D semiconductor technologies that allow the industry to scale beyond the limitations of Moore's Law. We are also very proud of the 3D InCites Fabless of the Year and Process of the Year honors we have received."

ZiBond is a low temperature homogeneous (oxide to oxide) direct bonding technology that forms strong bonds between wafers or die with same or different coefficients of thermal expansion. DBI is a low temperature hybrid direct bonding technology that allows wafers, or die, to be bonded with exceptionally fine-pitch 3D electrical interconnect. These platform technologies are applicable to a wide range of semiconductor devices including Image Sensors, MEMS, RF Front Ends, and Memory.

About Xperi Corporation

Xperi Corporation (Nasdaq:XPER) and its wholly owned subsidiaries, DTS, FotoNation, Invensas and Tessera, are dedicated to creating innovative technology solutions that enable extraordinary experiences for people around the world. Xperi's solutions are licensed by hundreds of leading global partners and have shipped in billions of products in areas including premium audio, broadcast, computational imaging, computer vision, mobile computing and communications, memory, data storage, and 3D semiconductor interconnect and packaging. For more information, please call +1 408-321-6000 or visit www.xperi.com.

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